
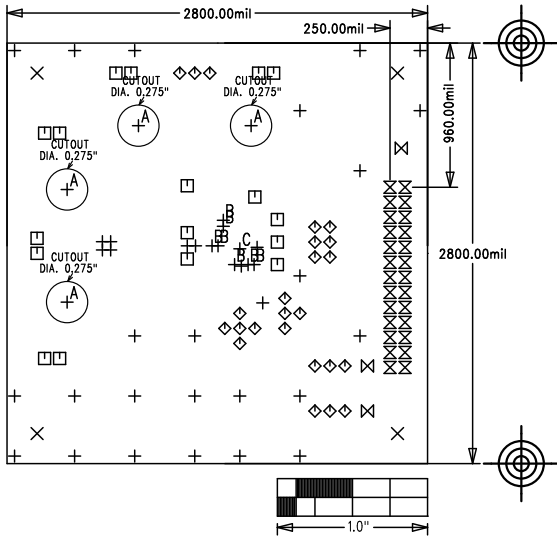


MAX98357 TQFN EVKIT - DEVELOPMENT BOARD	
P/N: EPCB98357DEVTQFN	REV A
	
LAYER DRILL & MECHANICALS	
DATE:	ALL UNITS ARE IN 0.001"



NOTES: UNLESS OTHERWISE SPECIFIED

1. FABRICATE USING PROVIDED GERBER FILES PER LATEST REVISION OF IPC-A-600 UNLESS OTHERWISE NOTED.
2. MATERIAL: RoHS COMPLIANT FR-408 OR SIMILAR LAMINATE MATERIAL WITH $T_g \geq 170$ AND COMPATIBLE WITH LEAD-FREE SOLDERING PROCESS.
3. BOARD DIMENSIONS: 2.80"X2.80" +/- 0.010".
BOARD THICKNESS: 0.062"
4. LAYERS: 4. SEE LAYER STACKUP CHART.
5. MINIMUM TRACE/SPACING: 10MILS/8MILS.
6. COPPER CLAD FINISH: 1oz ON ALL LAYERS.
7. SURFACE MOUNT PADS: 69.
8. SOLDERMASK: GREEN LPI SMOBC.
9. LEGENDS: WHITE. SINGLE-SIDED. NON-CONDUCTIVE EPOXY INK OR EQUIVALENT. CLIPPED ALL LEGENDS FROM EXPOSED METAL.
10. PLATING: MUST BE LEAD FREE AND RoHS COMPLIANT.
11. FINISH: VENDOR SHOULD USE THE MOST ECONOMICAL LEAD FREE AND RoHS COMPLIANT PROCESS AVAILABLE OR AS SPECIFIED IN PURCHASE ORDER.
APPROVED FINISH:
HASL LEAD-FREE
IMMERSION TIN
IMMERSION GOLD
12. VENDOR LOGO & DATE CODE REQUIRED IN INK ON BOTTOM SIDE ONLY. DATE CODE FORMAT MUST BE YYYYW ONLY.
13. THRU HOLES: 0.001" MIN.
14. TOLERANCES:
PLATED-THRU HOLES: +/-0.003"
PATTERN-TO-PATTERN: +/-0.005"
LEGEND TO LEGEND: +/-0.007"
SOLDERMASK TO PATTERN: +/-0.005"

LAYER 1 TOP	1.4MIL
PRE-PREG AS NEEDED	
LAYER 2 GND	1.4MIL
CORE AS NEEDED	
LAYER 3 PWR/GND	1.4MIL
PRE-PREG AS NEEDED	
LAYER 4 BOTTOM	1.4MIL

ALL DIMENSION IN MIL (0.001 INCH) UNLESS OTHERWISE SPECIFIED.

SIZE	QTY	SYM	PLATED	TOL
25	33	+	YES	+/-3
125	4	X	YES	+/-3
40	17	□	YES	+/-3
37	24	◇	YES	+/-3
43.31	26	⊗	YES	+/-3
67	3	⊗	YES	+/-3
275	4	⊕ ^A	YES	+/-3
15	7	⊕ ^B	YES	+/-3
20	1	⊕ ^C	YES	+/-3